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Intel - 5SGXEA5N3F45C2L Datasheet



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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

D	e	ta	il	ls

Details	
Product Status	Obsolete
Number of LABs/CLBs	185000
Number of Logic Elements/Cells	490000
Total RAM Bits	46080000
Number of I/O	840
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1932-BBGA, FCBGA
Supplier Device Package	1932-FBGA, FC (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxea5n3f45c2l

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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Transceiver Speed				Core Spe	ed Grade			
Grade	C1	C2, C2L	C3	C4	12, 12L	13, 13L	I 3YY	14
3		Yes	Yes	Yes		Yes	Yes (4)	Yes
GX channel—8.5 Gbps		165	165	165		163	163 17	165

Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering ^{(1), (2), (3)} (Part 2 of 2)

Notes to Table 1:

(1) C = Commercial temperature grade; I = Industrial temperature grade.

(2) Lower number refers to faster speed grade.

(3) C2L, I2L, and I3L speed grades are for low-power devices.

(4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices. **Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering** ⁽¹⁾, ⁽²⁾

Transaction Oracle Oracle	Core Speed Grade						
Transceiver Speed Grade	C1	C2	12	13			
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	_	_			
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes			

Notes to Table 2:

(1) C = Commercial temperature grade; I = Industrial temperature grade.

(2) Lower number refers to faster speed grade.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3.	Absolute	Maximum	Ratings	for Stratix \	/ Devices	(Part 1 of 2)
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Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Power supply for core voltage and periphery circuitry	-0.5	1.35	V
V _{CCPT}	Power supply for programmable power technology	-0.5	1.8	V
V _{CCPGM}	Power supply for configuration pins	-0.5	3.9	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	-0.5	3.4	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	-0.5	3.9	V
V _{CCPD}	I/O pre-driver power supply	-0.5	3.9	V
V _{CCIO}	I/O power supply	-0.5	3.9	V

Symbol	Description	Minimum	Maximum	Unit
V _{CCD_FPLL}	PLL digital power supply	-0.5	1.8	V
V _{CCA_FPLL}	PLL analog power supply	-0.5	3.4	V
VI	DC input voltage	-0.5	3.8	V
TJ	Operating junction temperature	-55	125	°C
T _{STG}	Storage temperature (No bias)	-65	150	°C
I _{OUT}	DC output current per pin	-25	40	mA

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 2 of 2)

Table 4 lists the absolute conditions for the transceiver power supply for Stratix V GX, GS, and GT devices.

Table 4. Transceiver Power Supply Absolute Conditions for Stratix V GX, GS, and GT Devices

Symbol	Description	Devices	Minimum	Maximum	Unit
V _{CCA_GXBL}	Transceiver channel PLL power supply (left side)	GX, GS, GT	-0.5	3.75	V
V _{CCA_GXBR}	Transceiver channel PLL power supply (right side)	GX, GS	-0.5	3.75	V
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	-0.5	3.75	V
V _{CCHIP_L}	Transceiver hard IP power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCHIP_R}	Transceiver hard IP power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCHSSI_L}	Transceiver PCS power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCHSSI_R}	Transceiver PCS power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GXBL}	Receiver analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GXBR}	Receiver analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V _{CCT_GXBL}	Transmitter analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCT_GXBR}	Transmitter analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V _{CCL_GTBR}	Transmitter clock network power supply (right side)	GT	-0.5	1.35	V
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	-0.5	1.8	V
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	-0.5	1.8	V

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage shown in Table 5 and undershoot to -2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

Table 5 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle. For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

abic J. Maxi				
Symbol	Description	Condition (V)	Overshoot Duration as % @ T _J = 100°C	Unit
		3.8	100	%
		3.85	64	%
		3.9	36	%
		3.95	21	%
Vi (AC)	AC input voltage	4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

Table 5. Maximum Allowed Overshoot During Transitions

Figure 1. Stratix V Device Overshoot Duration



Internal Weak Pull-Up Resistor

Table 16 lists the weak pull-up resistor values for Stratix V devices.

Symbol	Description	V _{CCIO} Conditions (V) ⁽³⁾	Value ⁽⁴⁾	Unit
		3.0 ±5%	25	kΩ
		2.5 ±5%	25	kΩ
	Value of the I/O pin pull-up resistor before	1.8 ±5%	25	kΩ
R _{PU}	and during configuration, as well as user mode if you enable the programmable	1.5 ±5%	25	kΩ
	pull-up resistor option.	1.35 ±5%	25	kΩ
		1.25 ±5%	25	kΩ
		1.2 ±5%	25	kΩ

Table 16. Internal Weak Pull-Up Resistor for Stratix V Devices (1), (2)

Notes to Table 16:

(1) All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins.

(2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 k Ω .

- (3) The pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.
- (4) These specifications are valid with a $\pm 10\%$ tolerance to cover changes over PVT.

I/O Standard Specifications

Table 17 through Table 22 list the input voltage (V_{IH} and V_{IL}), output voltage (V_{OH} and V_{OL}), and current drive characteristics (I_{OH} and I_{OL}) for various I/O standards supported by Stratix V devices. These tables also show the Stratix V device family I/O standard specifications. The V_{OL} and V_{OH} values are valid at the corresponding I_{OH} and I_{OL}, respectively.

For an explanation of the terms used in Table 17 through Table 22, refer to "Glossary" on page 65. For tolerance calculations across all SSTL and HSTL I/O standards, refer to Altera knowledge base solution rd07262012_486.

I/O		V _{ccio} (V)		V	L (V)	VIH	(V)	V _{OL} (V)	V _{OH} (V)	IOL	I _{oh}
Standard	Min	Тур	Max	Min	Max	Min	Max	Max	Min	(mĀ)	(mÅ)
LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	$V_{CCI0} - 0.2$	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	0.35 * V _{CCI0}	0.65 * V _{CCI0}	V _{CCI0} + 0.3	0.45	V _{CCI0} – 0.45	2	-2
1.5 V	1.425	1.5	1.575	-0.3	0.35 * V _{CCI0}	0.65 * V _{CCI0}	V _{CCI0} + 0.3	0.25 * V _{CCI0}	0.75 * V _{CCIO}	2	-2
1.2 V	1.14	1.2	1.26	-0.3	0.35 * V _{CCI0}	0.65 * V _{CCIO}	V _{CCI0} + 0.3	0.25 * V _{CCI0}	0.75 * V _{CCI0}	2	-2

Table 17. Single-Ended I/O Standards for Stratix V Devices

- You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.
- ***** For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Symbol/			Trai	Transceiver Speed Grade 2			Transceiver Speed Grade 3				
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Spread-spectrum downspread	PCle	_	0 to 0.5	_	_	0 to 0.5		_	0 to 0.5	_	%
On-chip termination resistors ⁽²¹⁾	_	_	100		_	100		_	100		Ω
Absolute V _{MAX} ⁽⁵⁾	Dedicated reference clock pin	_	_	1.6	_	_	1.6	_	_	1.6	V
	RX reference clock pin	_	_	1.2	_		1.2		_	1.2	
Absolute V_{MIN}	—	-0.4	—		-0.4	—	—	-0.4	—	—	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	200	_	1600	mV
V _{ICM} (AC clock pin		1050/1000/900/850 ⁽²⁾ 1				1000/90	00/850 ⁽²⁾	1050/	1000/90	00/850 ⁽²⁾	mV
coupled) ⁽³⁾	RX reference clock pin	1.	.0/0.9/0	.85 ⁽⁴⁾	1.	0/0.9/0	.85 ⁽⁴⁾	1.	0/0.9/0	.85 ⁽⁴⁾	V
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250		550	250		550	250		550	mV
	100 Hz	—	—	-70	—	—	-70	—	—	-70	dBc/Hz
Transmitter	1 kHz			-90			-90		—	-90	dBc/Hz
REFCLK Phase Noise	10 kHz	—	—	-100	—	—	-100	—	—	-100	dBc/Hz
(622 MHz) ⁽²⁰⁾	100 kHz			-110	—	—	-110	—	—	-110	dBc/Hz
	≥1 MHz	—	—	-120	—	—	-120	—	—	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁷⁾	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	_	_	3	ps (rms)
R _{REF} (19)	_		1800 ±1%		_	1800 ±1%	_		180 0 ±1%		Ω
Transceiver Clocks	S										
fixedclk clock frequency	PCIe Receiver Detect		100 or 125	_	_	100 or 125	_	_	100 or 125	_	MHz

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 2 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	isceive Grade	er Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Reconfiguration clock (mgmt_clk_clk) frequency	_	100	_	125	100		125	100		125	MHz
Receiver											
Supported I/O Standards	_		1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS								
Data rate (Standard PCS) (9), (23)	_	600	_	12200	600	_	12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS) ^{(9),} ⁽²³⁾		600	_	14100	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
Absolute V_{MAX} for a receiver pin (5)		_	_	1.2	—	_	1.2	—	_	1.2	V
Absolute V _{MIN} for a receiver pin	_	-0.4	_		-0.4	_	_	-0.4	_	_	V
Maximum peak- to-peak differential input voltage V _{ID} (diff p- p) before device configuration ⁽²²⁾	_	_	_	1.6	_	_	1.6	_	_	1.6	V
Maximum peak- to-peak	V _{CCR_GXB} = 1.0 V/1.05 V (V _{ICM} = 0.70 V)	_	_	2.0	_	_	2.0	_	_	2.0	V
differential input voltage V_{ID} (diff p- p) after device configuration ⁽¹⁸⁾ ,	$V_{CCR_GXB} = 0.90 V$ (V _{ICM} = 0.6 V)	_	_	2.4	_	_	2.4	_	_	2.4	V
(22)	$V_{CCR_GXB} = 0.85 V$ (V _{ICM} = 0.6 V)			2.4			2.4			2.4	V
Minimum differential eye opening at receiver serial input pins ^{(6), (22),} (27)	_	85		_	85	_	_	85	_	_	mV

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 3 of 7)

Symbol/ Description	Conditions	Trai	nsceive Grade	r Speed 1	Trar	isceive Grade	r Speed 2	Transceiver Speed Grade 3		Unit	
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t _{pll_lock} (16)	_			10		—	10	—		10	μs

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 7 of 7)

Notes to Table 23:

(2) The reference clock common mode voltage is equal to the V_{CCR_GXB} power supply level.

(3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.

- (4) This supply follows VCCR_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t_{LTD} is time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high.
- (13) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14) $t_{LTR_LTD_manual}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15) $t_{pll_powerdown}$ is the PLL powerdown minimum pulse width.
- (16) t_{pll lock} is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCIe at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (19) For ES devices, R_{BEF} is 2000 $\Omega \pm 1\%$.
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

⁽¹⁾ Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the Stratix V Device Overview.

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 5 of 5) (Fransceiver Specifications for Stratix V GT Devices (Part 5 of 5) ⁽¹⁾
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Symbol/ Description	Conditions		Transceivei peed Grade		S	Unit			
Description		Min	Тур	Max	Min Typ Max		Max]	
t _{pll_lock} ⁽¹⁴⁾	—	—	_	10	—	—	10	μs	

Notes to Table 28:

- (1) Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the Stratix V Device Overview.
- (2) The reference clock common mode voltage is equal to the VCCR_GXB power supply level.
- (3) The device cannot tolerate prolonged operation at this absolute maximum.
- (4) The differential eye opening specification at the receiver input pins assumes that receiver equalization is disabled. If you enable receiver equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (5) Refer to Figure 5 for the GT channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (6) Refer to Figure 6 for the GT channel DC gain curves.
- (7) CFP2 optical modules require the host interface to have the receiver data pins differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (8) Specifications for this parameter are the same as for Stratix V GX and GS devices. See Table 23 for specifications.
- (9) t_{1 TR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (10) t_{LTD} is time required for the receiver CDR to start recovering valid data after the rx is lockedtodata signal goes high.
- (11) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (12) t_{LTR_LTD_manual} is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (13) tpll_powerdown is the PLL powerdown minimum pulse width.
- (14) tpll lock is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (15) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (16) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (17) For ES devices, RREF is 2000 $\Omega \pm 1\%$.
- (18) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (19) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (20) Refer to Figure 4.
- (21) For oversampling design to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (22) This supply follows VCCR_GXB for both GX and GT channels.
- (23) When you use fPLL as a TXPLL of the transceiver.

Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit	
Modes using Three DSPs									
One complex 18 x 25	425	425	415	340	340	275	265	MHz	
Modes using Four DSPs									
One complex 27 x 27	465	465	465	380	380	300	290	MHz	

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)

Memory Block Specifications

Table 33 lists the Stratix V memory block specifications.

Table 33. Memory Block Performance Specifications for Stratix V Devices ^{(1), (2)} (Part 1 of 2)

		Resour	ces Used		Performance								
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, 12L	13, 13L, 13YY	14	Unit		
	Single port, all supported widths	0	1	450	450	400	315	450	400	315	MHz		
MLAB	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	MHz		
IVILAD	Simple dual-port, x16 depth ⁽³⁾	0	1	675	675	533	400	675	533	400	MHz		
	ROM, all supported widths	0	1	600	600	500	450	600	500	450	MHz		

Periphery Performance

This section describes periphery performance, including high-speed I/O and external memory interface.

I/O performance supports several system interfaces, such as the **LVDS** high-speed I/O interface, external memory interface, and the **PCI/PCI-X** bus interface. General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-**LVTTL/LVCMOS** are capable of a typical 167 MHz and 1.2-**LVCMOS** at 100 MHz interfacing frequency with a 10 pF load.

The actual achievable frequency depends on design- and system-specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

High-Speed I/O Specification

Table 36 lists high-speed I/O timing for Stratix V devices.

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 1 of 4)

Sumbol	Conditiono		C1		C2,	C2L, I	2, I2L	C3,	13, 13L	., I 3YY		C4,I	4	Ilmit
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{HSCLK_in} (input clock frequency) True Differential I/O Standards	Clock boost factor W = 1 to 40 $^{(4)}$	5		800	5		800	5		625	5		525	MHz
f _{HSCLK_in} (input clock frequency) Single Ended I/O Standards ⁽³⁾	Clock boost factor W = 1 to 40 $^{(4)}$	5		800	5	_	800	5		625	5		525	MHz
f _{HSCLK_in} (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 $^{(4)}$	5		520	5	_	520	5		420	5		420	MHz
f _{HSCLK_OUT} (output clock frequency)	_	5	_	800	5	_	800	5	_	625 (5)	5	_	525 (5)	MHz

Gumbal	Oenditione		C1		C2,	C2L, I	2, I2L	C3,	13, I3L	., I3YY		C4,I	4	Unit
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Min Typ Max		Unit
	SERDES factor J = 3 to 10	(6)	_	(8)	(6)	_	(8)	(6)		(8)	(6)		(8)	Mbps
f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)		(7)	(6)	_	(7)	(6)		(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)		(7)	Mbps
DPA Mode														
DPA run length	_			1000 0		_	1000 0		_	1000 0		_	1000 0	UI
Soft CDR mode)													
Soft-CDR PPM tolerance	_	_	_	300	_	—	300	_		300	_		300	± PPM
Non DPA Mode	•	•		-		-		•		-			-	-
Sampling Window	_			300			300			300			300	ps

Table 36. High-Speed I/O Specifications for Stratix V Devices ^{(1), (2)} (Part 4 of 4)

Notes to Table 36:

(1) When J = 3 to 10, use the serializer/deserializer (SERDES) block.

(2) When J = 1 or 2, bypass the SERDES block.

(3) This only applies to DPA and soft-CDR modes.

(4) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.

(5) This is achieved by using the **LVDS** clock network.

(6) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.

(7) The maximum ideal frequency is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.

(8) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.

(9) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.

(10) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.

(11) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design-dependent and requires timing analysis.

(12) Stratix V RX LVDS will need DPA. For Stratix V TX LVDS, the receiver side component must have DPA.

(13) Stratix V LVDS serialization and de-serialization factor needs to be x4 and above.

(14) Requires package skew compensation with PCB trace length.

(15) Do not mix single-ended I/O buffer within LVDS I/O bank.

(16) Chip-to-chip communication only with a maximum load of 5 pF.

(17) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

Clock Network	Parameter	Symbol	C1 C2, C2L, I2, I2L		C3, I3 I3		C4	Unit			
NELWURK		-	Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	$t_{JIT(per)}$	-25	25	-25	25	-30	30	-35	35	ps
PHY Clock	Cycle-to-cycle period jitter	$t_{\text{JIT(cc)}}$	-50	50	-50	50	-60	60	-70	70	ps
	Duty cycle jitter	$t_{\text{JIT}(\text{duty})}$	-37.5	37.5	-37.5	37.5	-45	45	-56	56	ps

Table 42. Memory Output Clock Jitter Specification for Stratix V Devices (1), (Part 2 of 2) (2), (3)

Notes to Table 42:

(1) The clock jitter specification applies to the memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a PHY, regional, or global clock network as specified. Altera recommends using PHY clock networks whenever possible.

(2) The clock jitter specification applies to the memory output clock pins clocked by an integer PLL.

(3) The memory output clock jitter is applicable when an input jitter of 30 ps peak-to-peak is applied with bit error rate (BER) -12, equivalent to 14 sigma.

OCT Calibration Block Specifications

Table 43 lists the OCT calibration block specifications for Stratix V devices.

Table 43. OCT Calibration Block Specifications for Stratix V Devices

Symbol	Description	Min	Тур	Max	Unit
OCTUSRCLK	Clock required by the OCT calibration blocks		_	20	MHz
T _{OCTCAL}	Number of OCTUSRCLK clock cycles required for OCT $\rm R_S/R_T$ calibration	_	1000	_	Cycles
T _{OCTSHIFT}	Number of OCTUSRCLK clock cycles required for the OCT code to shift out	—	32	_	Cycles
T _{RS_RT}	Time required between the dyn_term_ctrl and oe signal transitions in a bidirectional I/O buffer to dynamically switch between OCT R_S and R_T (Figure 10)	_	2.5		ns

Figure 10 shows the timing diagram for the oe and dyn_term_ctrl signals.

Figure 10. Timing Diagram for oe and dyn_term_ctrl Signals



Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
FFF X02	Enabled	Disabled	8
	Enabled	Enabled	8

Note to Table 49:

(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host



Notes to Figure 11:

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V_{CCPGM} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V_{CCPGM} .
- (2) You can leave the nCEO pin unconnected or use it as a user I/O pin when it does not feed another device's nCE pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP ×8, use DATA [7..0]. If you use FPP ×16, use DATA [15..0].

IF the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio – 1) clock cycles after the last data is latched into the Stratix V device.

FPP Configuration Timing when DCLK-to-DATA [] = 1

Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA[] ratio is 1.





Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA [] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nstatus low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF_DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP ×16, use DATA [15..0]. For FPP ×8, use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the INIT_DONE pin is configured into the device, the INIT DONE goes low.

Active Serial Configuration Timing

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

Table 52.	DCLK Frequency	Specification in the <i>l</i>	AS Configuration Scheme	(1), (2)
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Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

Notes to Table 52:

(1) This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.

(2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.





Notes to Figure 14:

- (1) If you are using AS $\times 4$ mode, this signal represents the AS_DATA[3..0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (2) The initialization clock can be from internal oscillator or CLKUSR pin.
- (3) After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Table 53 lists the timing parameters for AS $\times 1$ and AS $\times 4$ configurations in Stratix V devices.

Symbol	Parameter	Minimum	Maximum	Units
t _{CO}	DCLK falling edge to AS_DATA0/ASDO output	—	2	ns
t _{SU}	Data setup time before falling edge on DCLK	1.5	_	ns
t _H	Data hold time after falling edge on DCLK	0	_	ns

Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions
G		
Н	_	_
Ι		
J	J JTAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus). JTAG Timing Specifications: TMS TDI t_{JCP} t_{JCP} t_{JPCO} t_{JPCO} t_{JPXZ} TDO t_{JPXZ} t_{JPXZ}
K L M N O	_	_
Ρ	PLL Specifications	Diagram of PLL Specifications (1)
Q		_
	1	

Letter	Subject	Definitions
	V _{CM(DC)}	DC common mode input voltage.
	V _{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.
	V _{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	V _{DIF(AC)}	AC differential input voltage—Minimum AC input differential voltage required for switching.
	V _{DIF(DC)}	DC differential input voltage— Minimum DC input differential voltage required for switching.
	V _{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	V _{IH(AC)}	High-level AC input voltage
	V _{IH(DC)}	High-level DC input voltage
V	V _{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	V _{IL(AC)}	Low-level AC input voltage
	V _{IL(DC)}	Low-level DC input voltage
	V _{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.
	V _{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
	V _{SWING}	Differential input voltage
	V _X	Input differential cross point voltage
	V _{OX}	Output differential cross point voltage
W	W	High-speed I/O block—clock boost factor
X		
Y	_	_
Z		

Table 60. Glossary (Part 4 of 4)

Document Revision History

Table 61 lists the revision history for this chapter.

 Table 61. Document Revision History (Part 1 of 3)

Date	Version	Changes	
June 2018	3.9	 Added the "Stratix V Device Overshoot Duration" figure. 	
		 Added a footnote to the "High-Speed I/O Specifications for Stratix V Devices" table. 	
	3.8	 Changed the minimum value for t_{CD2UMC} in the "PS Timing Parameters for Stratix V Devices" table. 	
		 Changed the condition for 100-Ω R_D in the "OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices" table. 	
April 2017		 Changed the minimum value for t_{CD2UMC} in the "AS Timing Parameters for AS '1 and AS '4 Configurations in Stratix V Devices" table 	
		 Changed the minimum value for t_{CD2UMC} in the "FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1" table. 	
		 Changed the minimum value for t_{CD2UMC} in the "FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1" table. 	
		 Changed the minimum number of clock cycles value in the "Initialization Clock Source Option and the Maximum Frequency" table. 	
June 2016	3.7	 Added the V_{ID} minimum specification for LVPECL in the "Differential I/O Standard Specifications for Stratix V Devices" table 	
Julie 2010		 Added the I_{OUT} specification to the "Absolute Maximum Ratings for Stratix V Devices" table. 	
December 2015	3.6	Added a footnote to the "High-Speed I/O Specifications for Stratix V Devices" table.	
December 2015	3.5	 Changed the transmitter, receiver, and ATX PLL data rate specifications in the "Transceiver Specifications for Stratix V GX and GS Devices" table. 	
December 2015		 Changed the configuration .rbf sizes in the "Uncompressed .rbf Sizes for Stratix V Devices" table. 	
		• Changed the data rate specification for transceiver speed grade 3 in the following tables:	
		 "Transceiver Specifications for Stratix V GX and GS Devices" 	
	3.4	 "Stratix V Standard PCS Approximate Maximum Date Rate" 	
		 "Stratix V 10G PCS Approximate Maximum Data Rate" 	
July 2015		 Changed the conditions for reference clock rise and fall time, and added a note to the "Transceiver Specifications for Stratix V GX and GS Devices" table. 	
		 Added a note to the "Minimum differential eye opening at receiver serial input pins" specification in the "Transceiver Specifications for Stratix V GX and GS Devices" table. 	
		 Changed the t_{co} maximum value in the "AS Timing Parameters for AS '1 and AS '4 Configurations in Stratix V Devices" table. 	
		 Removed the CDR ppm tolerance specification from the "Transceiver Specifications for Stratix V GX and GS Devices" table. 	